



Date: September 6. 2016

Document: A

Rev: 1.0

Marking on device:

**VSXX05GF**  
**PPPPPPPPPP**  
**FFFFFF YYWW**

where, VSXX05GF = VS1205GF, VS1005GF or VS8005GF

PPPPPPPPPP = Lot ID

FFFFFF = leftmost characters of the flash (top die) Lot ID. If 2 different lots, then 3 characters of each lot.

YYWW = assembly Year and Week

**Order code:**

VS1205G-F-Q

VS1005G-F-Q

VS8005G-F-Q

**Product Name:**

VS1205G-F/LSR-ROHS

VS1005G-F/LSR-ROHS

VS8005G-F/LSR-ROHS

**Package:** 88 LFGA (10x10x0.8) C2TP0.40

**REF:**

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip							
		1. (Bottom die, VSX0X5G) - 204x205x7 mils	11.446	Silicon	7440-21-3	100.00	11.446	4.052	40523.843
		2. (Top die, Flash memory) - 85 x 59 x 7 mils	1.389	Silicon	7440-21-3	100.00	1.389	0.492	4917.667
2	Substrate (Lead Frame)	HDL (10X10) LF ((A194FH))	117.588	Copper	7440-50-8	97.150	114.237	40.445	404448.000
				Fe	7439-89-6	2.500	2.940	1.041	10407.823
				P	7723-14-0	0.150	0.176	0.062	624.469
				Zn	7440-66-6	0.150	0.176	0.062	624.469
				Silver	7440-22-4	0.050	0.059	0.021	208.156
3	Mold Compound	EME G770HP	144.016	Silica(Amorphous) A	60676-86-0	75.5	108.732	38.496	384959.090
				Silica(Amorphous) B	7631-86-9	15	21.602	7.648	76481.938
				Epoxy Resin A	Trade Secret	3.0	4.320	1.530	15296.388
				Epoxy Resin B	Trade Secret	3.0	4.320	1.530	15296.388
				Phenol Resin	Trade Secret	3.0	4.320	1.530	15296.388
				Carbon Black	1333-86-4	0.5	0.720	0.255	2549.398
4	Bonding Wire	Gold wire (25 microns)	0.953	Au	7440-57-5	99.99	0.953	0.337	3373.699
				Dopant	Trade Secret	0.01	0.00010	0.000	0.337
5	Die Attach Material (Bottom die, VSX0X5G)	CRM 1066C	2.314	Silver (Ag)	7440-22-4	72.000	1.666	0.590	5898.651
				Epoxy resin A	9003-36-5	15.000	0.347	0.123	1228.886
				Acid Anhydride A	19438-60-9	7.000	0.162	0.057	573.480
				Epoxy resin B	Trade Secret	3.000	0.069	0.025	245.777
				Acid Anhydride B	85-42-7	3.000	0.069	0.025	245.777
6	Die Attach Material (Top die, Flash memory)	QMI-536	0.492	Proprietary Filler	9002-84-0	45	0.221	0.078	783.853
				Proprietary Bismaleimide	Trade Secret	45	0.221	0.078	783.853
				Proprietary Polymer	Trade Secret	10	0.049	0.017	174.190
7	Plating (Solder)	Sn 100 %	4.253	Tin (Sn)	7440-31-5	99.99	4.253	1.506	15055.973
				Other	Trade Secret	0.01	0.00043	0.000	1.506
Total Unit Weight =			282.451				282.451	100	1000000